

Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
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EFS ID: 19519  
Application ID: 10065632  
Title of Invention: CHIP STRUCTURE WITH BUMPS  
AND A PROCESS FOR  
FABRICATING THE SAME  
First Named Inventor: CHAO-FU WENG  
Domestic/Foreign Application: Domestic Application  
Filing Date: null  
Effective Receipt Date: 2002-11-05  
Submission Type: Utility Patent Filing  
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Trademark Office, ou=Department of Commerce, o=U.S.  
Government, c=US  
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# TRANSMITTAL FORM



Electronic Version 1.0.3

Stylesheet Version: 1.0

Attorney Docket  
Number:

8012-US-  
PA

Submission Type: Utility Patent  
Filing

## CHIP STRUCTURE WITH BUMPS AND A PROCESS FOR FABRICATING THE SAME

First Named Inventor: Mr. CHAO-FU WENG

### SUBMITTED BY

Name:

Dr. BELINDA LEE

Registration Number:

46,863

Electronic Signature Mark: /Belinda  
Lee/

Date Signed: 20021105

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*I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.*

### Attached Files:

declaration

8012declaration1.tif

declaration

8012declaration2.tif



Comments:

COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

CHIP STRUCTURE WITH BUMPS AND A PROCESS FOR FABRICATING  
THE SAME

the specification of which

X is attached hereto.

\_\_\_\_\_ was filed on \_\_\_\_\_

as Application Serial No. \_\_\_\_\_ and was amended on \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

Number	Country	Date Filed(yyyy/mm/dd)	Yes	No
91100094	Taiwan, R.O.C.	2002/1/7	X	

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Belinda Lee (Reg. No. 46,863)  
Jiawei Huang (Reg. No. 43,330)  
Charles C.H. Wu (Reg. No. 39,081)

SEND CORRESPONDENCE TO:

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Belinda Lee

COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature: 1<sup>st</sup> Chao-Fu Weng Date: 2/20/2002

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# FEE TRANSMITTAL

Electronic Version 1.1.0

Stylesheet Version: 1.0

*Patent fees are subject to annual revisions on or about October 1st of each year.*

Large Entity

**TOTAL FEES AUTHORIZED: \$ 864**

## BANK (CREDIT) CARD INFORMATION:

Credit Card Number: 3109  
Expiration Date: 20030430  
Authorized Name: LEE, HUAI-LU  
Billing Address: 99999

## BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	1001	\$ 740

Subtotal For Basic Filing Fee: \$ 740

## EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 20	1202	\$ 18	0	\$ 0
Independent Claims: 4	1201	\$ 84	1	\$ 84

Subtotal For Extra Claims Fees: \$ 84

## ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	\$ 40	\$ 40

Subtotal For Additional Fees: \$ 40